



XO SPECIFICATION

Customer: _____
Customer P/N: _____
TKD P/N: XO32F012288GBHE001
Part Name: SMD XO 3225
Product Description: 12.288000MHz
Issue Date: 2021/10/28

CUSTOMER'S APPROVAL

(PLEASE RETURN A COPY WITH APPROVAL)

TKD Science and Technology Co.,Ltd
泰晶科技股份有限公司

Approved	Checked	Designer
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Rev.	Description of Revision History	Date	Designer	Checked By
A	New revision	2021/10/28	Li Yan	Zhan Chao



XO SPECIFICATION

1.Description : SMD Simple Packaged Xtal Oscillator 3225

2.Nominal Frequency : 12.288000MHz

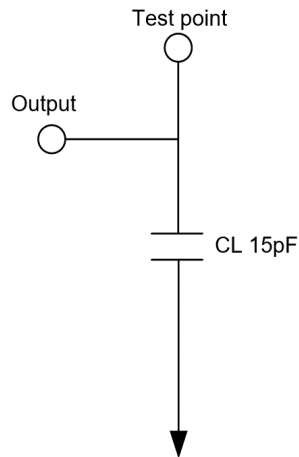
3.Electrical Specifications :

Item	Parameters	Condition	Electrical Specifications			
			Min	Typ	Max	Units
1	Nominal Frequency		12.288000			MHz
2	Frequency Tolerance	Note1	-50.0		50.0	ppm
3	Operating Temperature Range		-40		85	°C
4	Supply Voltage		3.3±10%			V
5	Current Consumption	Operating			15.0	mA
		Standby			10	uA
6	Output Waveform		CMOS			
7	Output Load		15			pF
8	Duty Cycle		50±10%			%
9	Output Rise/Fall Time				8.0	ns
10	High Output Voltage		0.9Vdd			V
11	Low Output Voltage				0.1Vdd	V
12	Enable		Vdd*70%			V
13	Disable				Vdd×30%	V
14	Aging	Frist year	-3.0		3.0	ppm
15	Storage Temperature		-55		125	°C

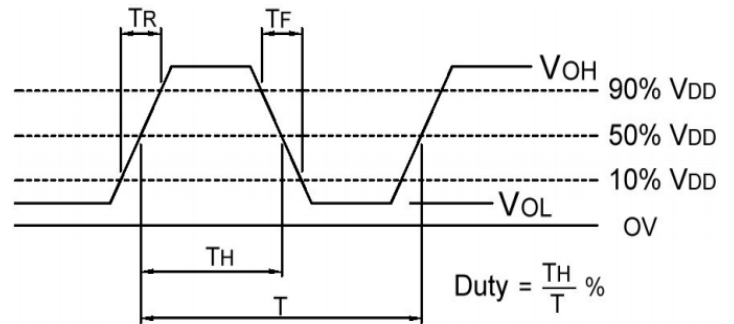
Note1 Frequency stability includes frequency tolerance@25°C and frequency stability vs. operating temperature range and voltage variance and first year aging



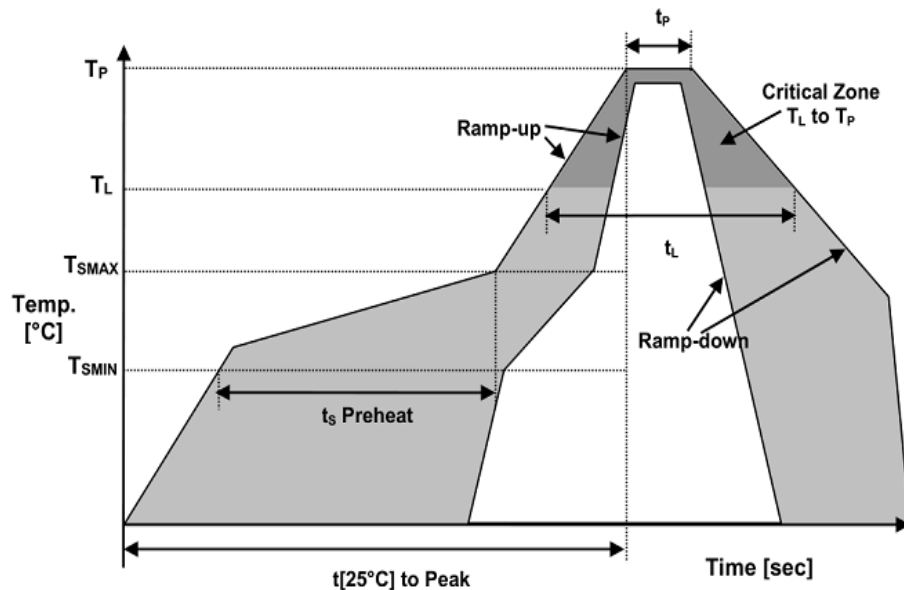
4.Test Circuit (CMOS Load)



5.Output Waveform (CMOS Load)



6.Recommended Reflow Profile

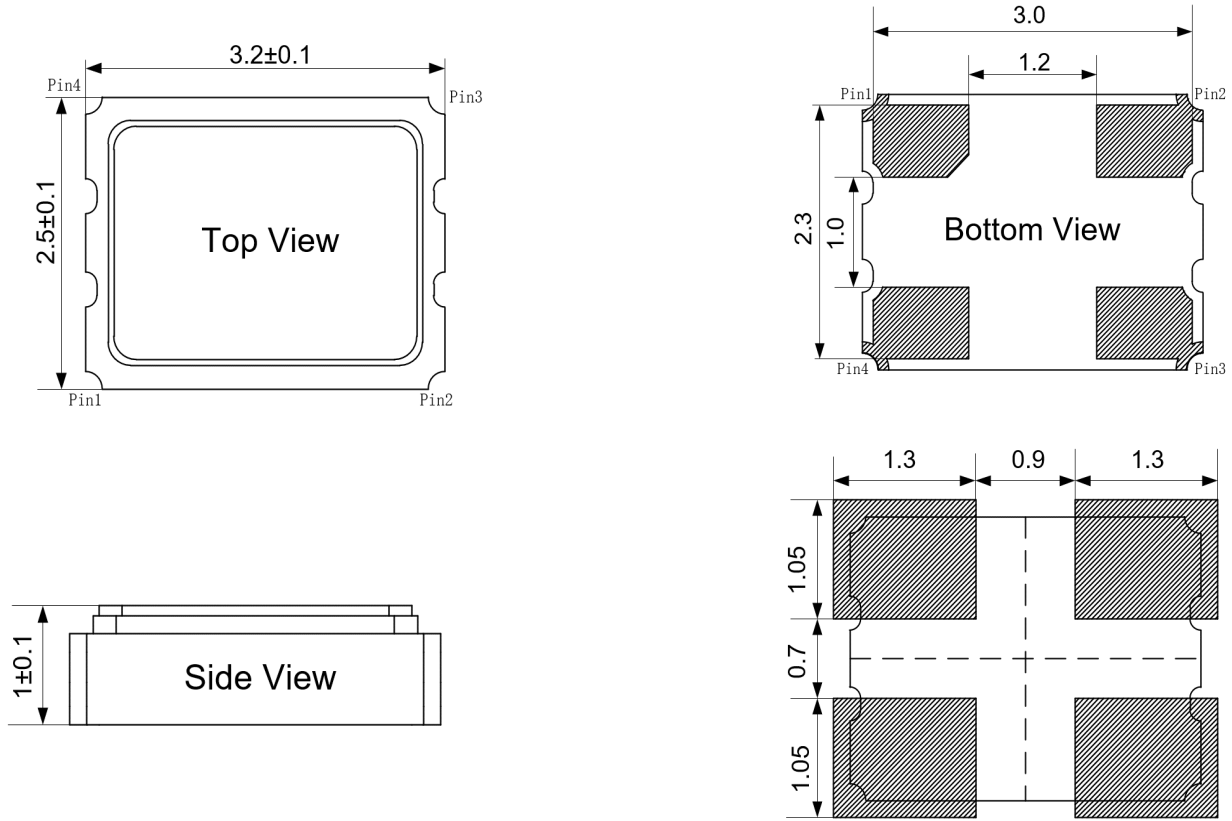


Reflow Profile		
Temperature MIN Preheat	T_{SMIN}	150°C
Temperature MAX Preheat	T_{SMAX}	200°C
Time ($T_{SMIN} - T_{SMAX}$)	t_s	60-180sec
Temperature	T_L	217°C
Peak Temperature	T_P	260°C
Ramp-up Rate	R_{UP}	3°C/sec max
Ramp-Down Rate	R_{DOWN}	6°C/sec max
Time within 5°C of Peak Temperature	t_p	10sec
Time $t(25^\circ\text{C})$ to Peak Temperature	$t(25^\circ\text{C})\text{to Peak}$	480sec
Time	t_L	60-150sec



7.Product Dimensions

Unit: mm



Recommend Soldering Pattern

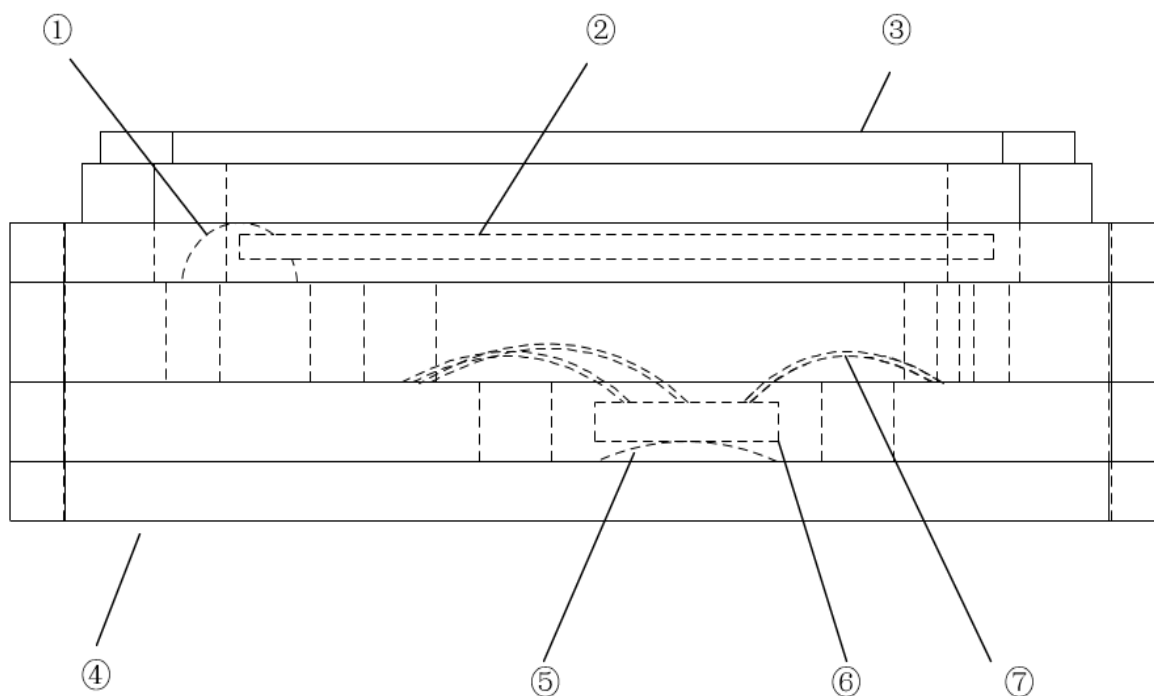
Pin Connection

Name	Connection
pin 1	Tri-State
pin 2	GND
pin 3	Fout
pin 4	Vdd

Function

Pin1 Input	Pin3 Output
High level	Oscillation Out
Low level	High Z

8. Structure illustration

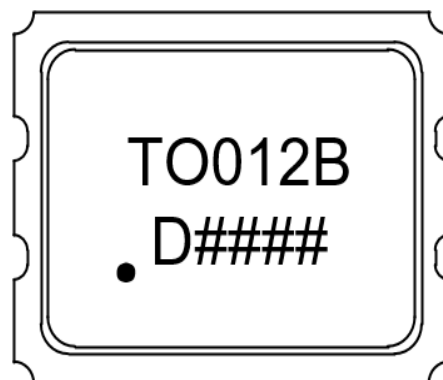


No.	Components	Materials
①	Conductive Adhesive	Ag+Silicone resin
②	Crystal Blank	SiO ₂
③	Lid	Fe-Ni-Co Alloy
④	Base	Ceramic+Noble Metal
⑤	Conductive Adhesive of Solid IC	Ag+Silicone resin
⑥	IC	Si
⑦	Gold wire	Au



9.Product Identification (Marking)

T: TKD Logo
O: Oscillator Code
012B: Frequency Code
●: Pin1 Index
D: Date Code
#####: XO Lot Code



Date Code

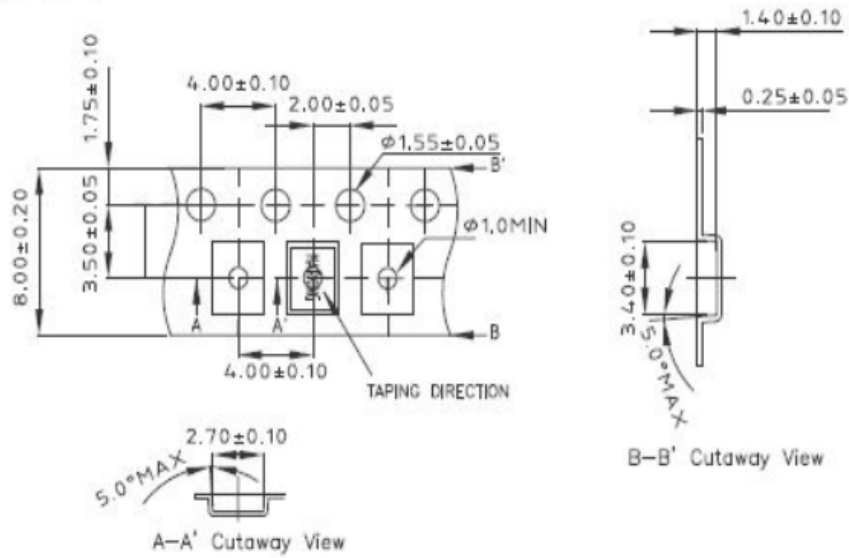
Year		2019	2020	2021	2022
		2023	2024	2025	2026
		2027	2028	2029	2030
		2031	2032	2033	2034
Month	JAN	a	n	A	N
	FEB	b	p	B	P
	MAR	c	q	C	Q
	APR	d	r	D	R
	MAY	e	s	E	S
	JUN	f	t	F	T
	JUL	g	u	G	U
	AUG	h	v	H	V
	SEP	j	w	J	W
	OCT	k	x	K	X
	NOV	l	y	L	Y
	DEC	m	z	M	Z

This date code will be cycled every four years.

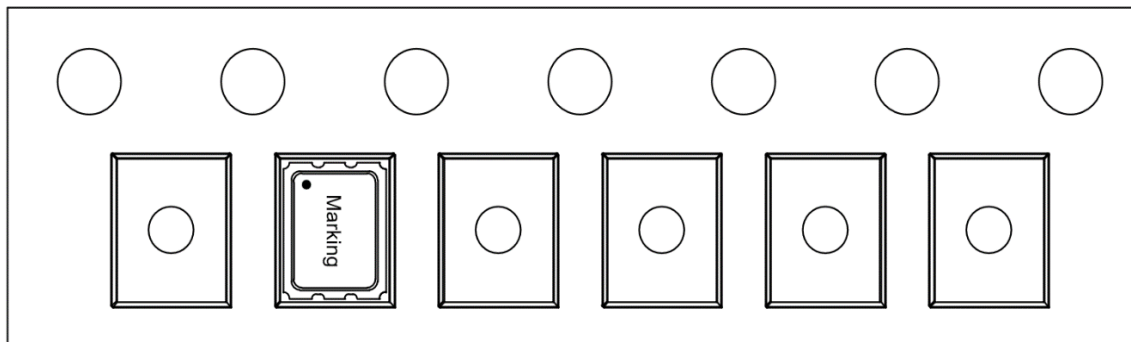
10.Package Information

Tape (Carrier) Dimensions

Unit: mm

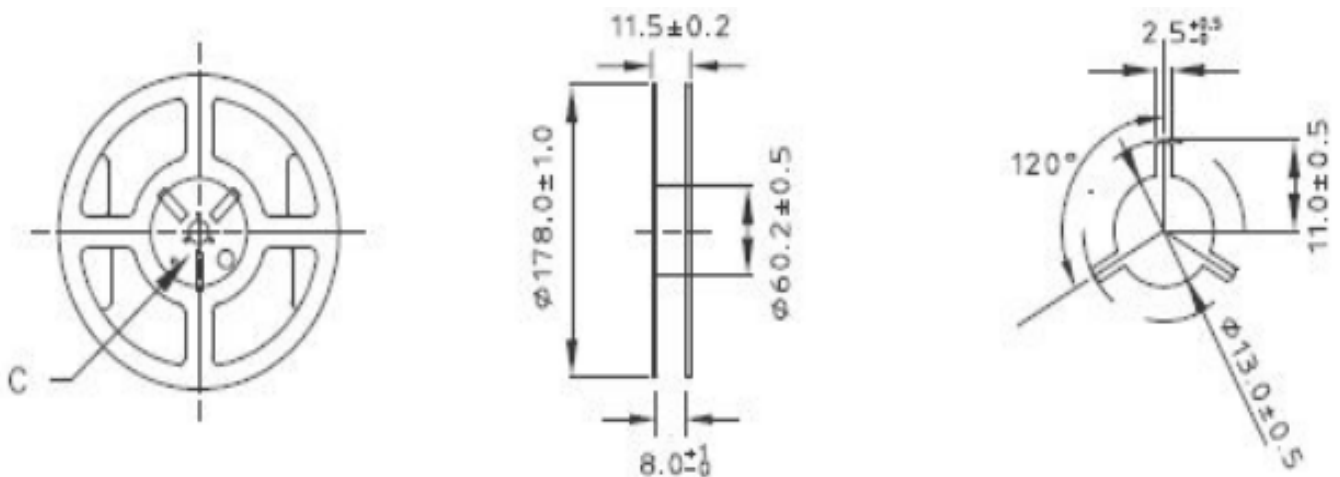


The Direction of Packing



Reel Dimensions

Unit: mm





Handling Instructions

1. Cautions for Handling

a) Prevention against electrostatic breakdown

Your full attention to static electricity is still requested.

b) Direction

Before mounting the crystal oscillator on board, Please confirm the direction to make sure the GND terminal and the terminal of power supply are not taken wrongly.

2. Prevention against Vibration and Shock

While the product is being transported or mounted onto board, if undue hock and vibration exceeding the specification is put on, there is risk hat the built-in crystal blank is broken.

When undue shock and vibration exceeding the specification is put on the product, please be sure to make confirmation of the product's characteristics.

3. Soldering

In order to assure the reliability of the crystal oscillator, please use the product under the recommended conditions.

4. Surface mounting

a) This product is surface-mounting device.

So, Please pay attention to the following things.

b) Extreme deformation of board may make pattern off, the electrode of terminals off and solder broken. Full attention is requested especially when splitting the board with the oscillator mounted where the camber of the board occurs.

c) In case that automatic mounter is used, please choose the type with small shock generation and make confirmation of the shock before use.

5. Cleaning

Because cleaning will cause change to all characteristics, cleaning is forbidden.

6. Store keeping (method and duration)

Long-time storage in the high/low temperature and high humidity leads to deterioration of solderability. So, please keep the product in the temperature of +5~+35 and humidity of 45~70%.

Moreover, please keep the product in the circumstance with measures against static electricity.

Please use it within 168 hours after the pack is opened.

(Please keep it with desiccator etc. when you exceed 168 hours after the bag is opened. Please use it after confirming the product solderability.)